

BYV10MB-600P

Ultrafast power diode Rev.01 - 08 October 2023

Product data sheet

1. General description

Ultrafast power diode in a TO263 plastic package.



2. Features and benefits

- Low leakage current
- · Low thermal resistance
- Low reverse recovery current
- Reduces switching losses in associated MOSFET or IGBT

3. Applications

- Active PFC in air conditioner/EV charger/PV
- Continuous Current Mode (CCM) Power Factor Correction (PFC)
- · Half-bridge/full-bridge switched-mode power supplies

4. Quick reference data

Table 1. Q	uick reference data						
Symbol	Parameter	Conditions	Notes		Values		Unit
Absolute	maximum rating						
V_{RRM}	repetitive peak reverse voltage				600		V
$I_{F(AV)}$	average forward current	δ = 0.5 ; square-wave pulse; T _{mb} ≤ 126 °C; Fig. 1; Fig. 2; Fig. 3		10			A
I _{FRM}	repetitive peak forward current	δ = 0.5 ; t _p = 25 μs; T _{mb} ≤ 126 °C; square-wave pulse		20			A
I _{FSM}	non-repetitive peak forward current	$t_{\rm p}$ = 10 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse; <u>Fig. 4</u>		100			A
		t_{p} = 8.3 ms; $T_{\text{j(init)}}$ = 25 °C; sine-wave pulse			110		А
Symbol	Parameter	Conditions	Notes	Min	Тур	Max	Unit
Static ch	aracteristics						
V _F	forward voltage	I _F = 10 A; T _j = 25 °C; <u>Fig. 6</u>		-	1.50	2.00	V
		I _F = 10 A; T _j = 150 °C; <u>Fig. 6</u>		-	-	1.60	V
Dynamic	characteristics						
t _{rr}	reverse recovery time	$I_F = 1 \text{ A}; V_R = 30 \text{ V}; dI_F/dt = 100 \text{ A}/\mu\text{s};$ $T_j = 25 \text{ °C}; Fig. 7$		-	27	-	ns

5. Pinning information

Table 2. F	Pinning infor	mation		
Pin	Symbol	Description	Simplified outline	Graphic symbol
1	nc	no connected		
2	К	cathode [1]		К <u>– Ң</u> А 001ааа020
3	А	anode	0	
mb	mb	mounting base; connected to cathod		

[1] It is not possible to connect to pin 2 of the TO-263 package.

6. Ordering information

Table 3. Ordering information								
Package	Orderable part number	Packing	Small packing	Package	Package			
name		method	quantity	version	issue date			
TO263	BYV10MB-600PJ	Reel	800	TO263d	17-Mar-2023			
	Package name	Package Orderable part number name	Package Orderable part number Packing method	Package name Orderable part number Packing method Small packing quantity	Package nameOrderable part number methodPacking methodSmall packing 			

7. Marking

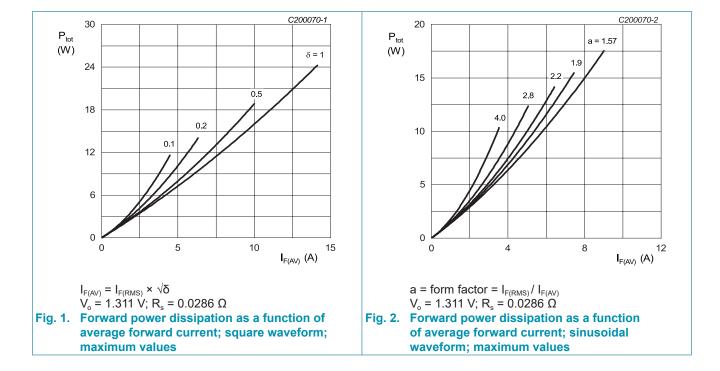
Table 4. Marking codes						
Type number	Marking codes					
BYV10MB-600P	BYV10MB 600P					

8. Limiting values

Table 5. Limiting values

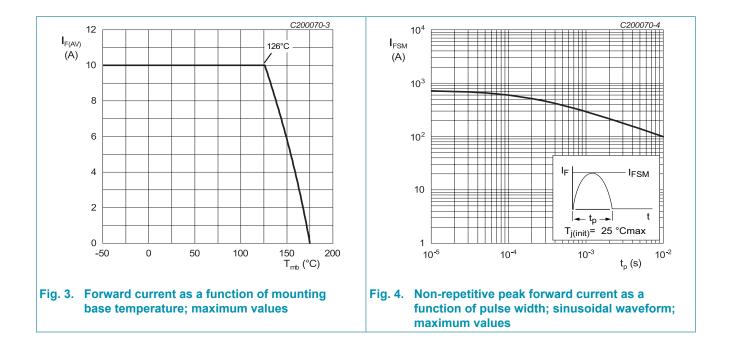
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Notes	Values	Unit
V _{RRM}	repetitive peak reverse voltage			600	V
V_{RWM}	crest working reverse voltage			600	V
V _R	reverse voltage	DC		600	V
I _{F(AV)}	average forward current	δ = 0.5 ; square-wave pulse; T _{mb} ≤ 126 °C; Fig. 1; Fig. 2; Fig. 3		10	A
I _{FRM}	repetitive peak forward current	δ = 0.5 ; t _p = 25 µs; T _{mb} ≤ 126 °C; square-wave pulse		20	A
I _{FSM}	non-repetitive peak forward current	t_p = 10 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse; Fig. 4		100	A
		t_p = 8.3 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse		110	А
T _{stg}	storage temperature			-65 to 175	°C
Tj	junction temperature			-65 to 175	°C



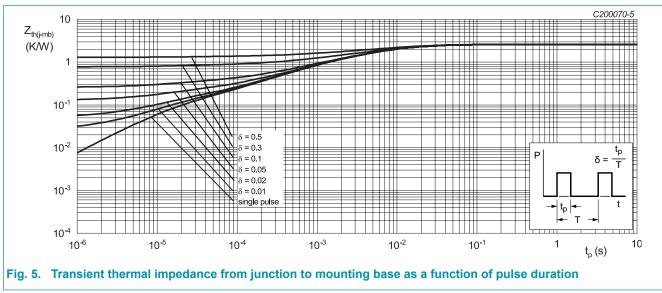
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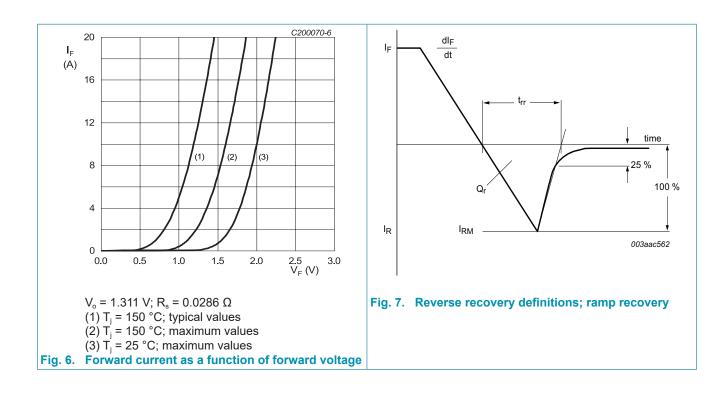
9. Thermal characteristics

Symbol	Parameter	Conditions	Notes	Min	Тур	Max	Unit
$R_{\text{th(j-mb)}}$	thermal resistance from junction to mounting base	<u>Fig. 5</u>		-	-	2.6	K/W
$R_{\text{th(j-a)}}$	thermal resistance from junction to ambient free air	in free air		-	60	-	K/W

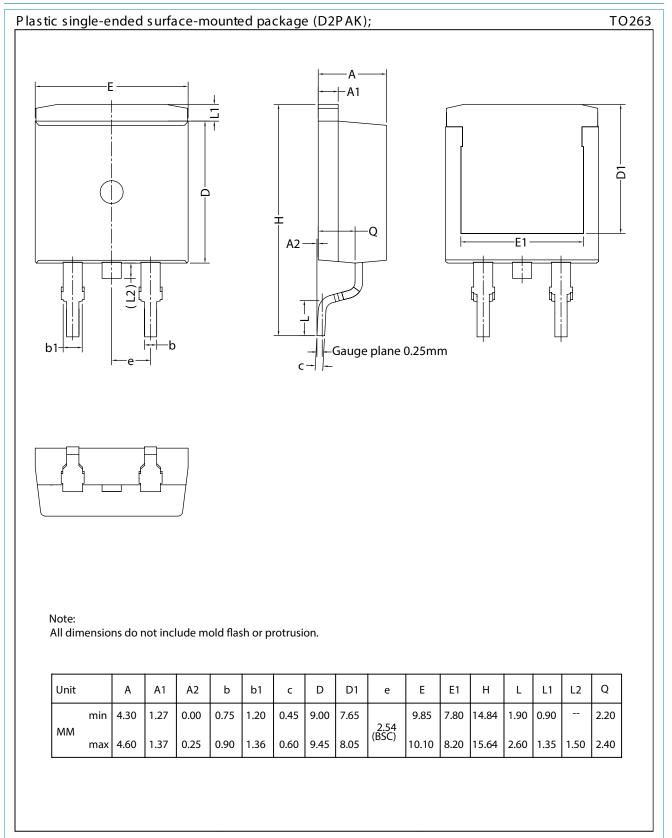


10. Characteristics

Symbol	Parameter	Conditions	Notes	Min	Тур	Max	Unit
Static ch	aracteristics				-		
V _F	forward voltage	I _F = 10 A; T _j = 25 °C; <u>Fig. 6</u>		-	1.50	2.00	V
		I _F = 10 A; T _j = 150 °C; <u>Fig. 6</u>		-	-	1.60	V
I _R	reverse current	V _R = 600 V; T _j = 25 °C		-	-	8	μA
		V _R = 600 V; T _j = 150 °C		-	-	120	μA
Dynamic	characteristics						
Q _r	reverse charge	$I_F = 10 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 200 \text{ A/}\mu\text{s};$ $T_j = 25 \text{ °C}; Fig. 7$		-	172	-	nC
		I _F = 10 A; V _R = 400 V; dI _F /dt = 200 A/µs; T _j = 125 °C; <u>Fig. 7</u>		-	380	-	nC
T _{rr}	reverse recovery time	I _F = 1 A; V _R = 30 V; dI _F /dt = 100 A/µs; T _j = 25 °C; <u>Fig. 7</u>		-	27	-	ns
		$I_F = 10 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 200 \text{ A/}\mu\text{s};$ $T_j = 25 \text{ °C}; Fig. 7$		-	58	-	ns
		I _F = 10 A; V _R = 400 V; dI _F /dt = 200 A/µs; T _j = 125 °C; <u>Fig. 7</u>		-	83	-	ns
I _{RM}	peak reverse recovery currentnon-repetitive avalanche energy	$I_F = 10 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 200 \text{ A/}\mu\text{s};$ $T_j = 25 \text{ °C}; Fig. 7$		-	5.6	-	A
		I _F = 10 A; V _R = 400 V; dI _F /dt = 200 A/μs; T _i = 125 °C; <u>Fig. 7</u>		-	8.7	-	A



11. Package outline



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Ultrafast power diode

12. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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